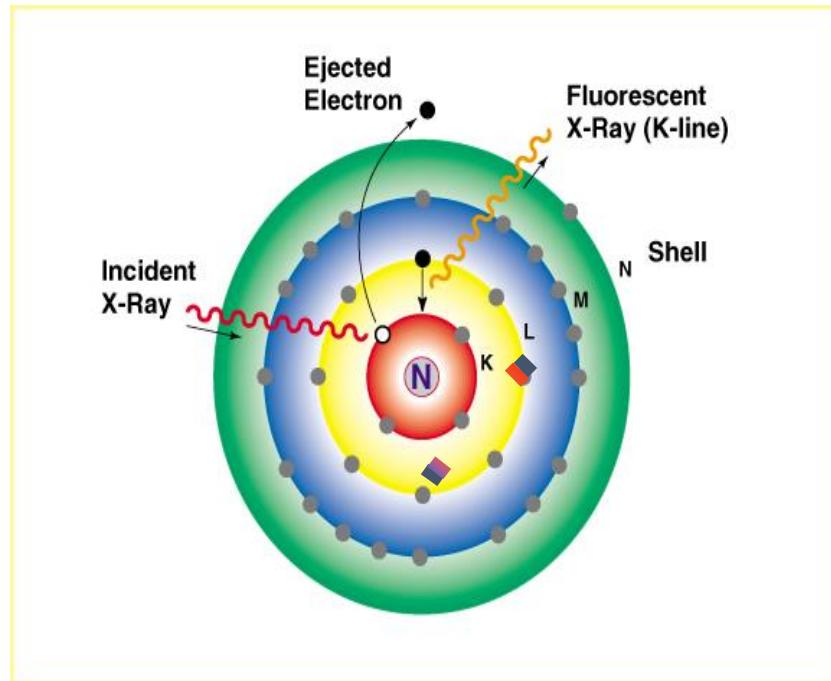


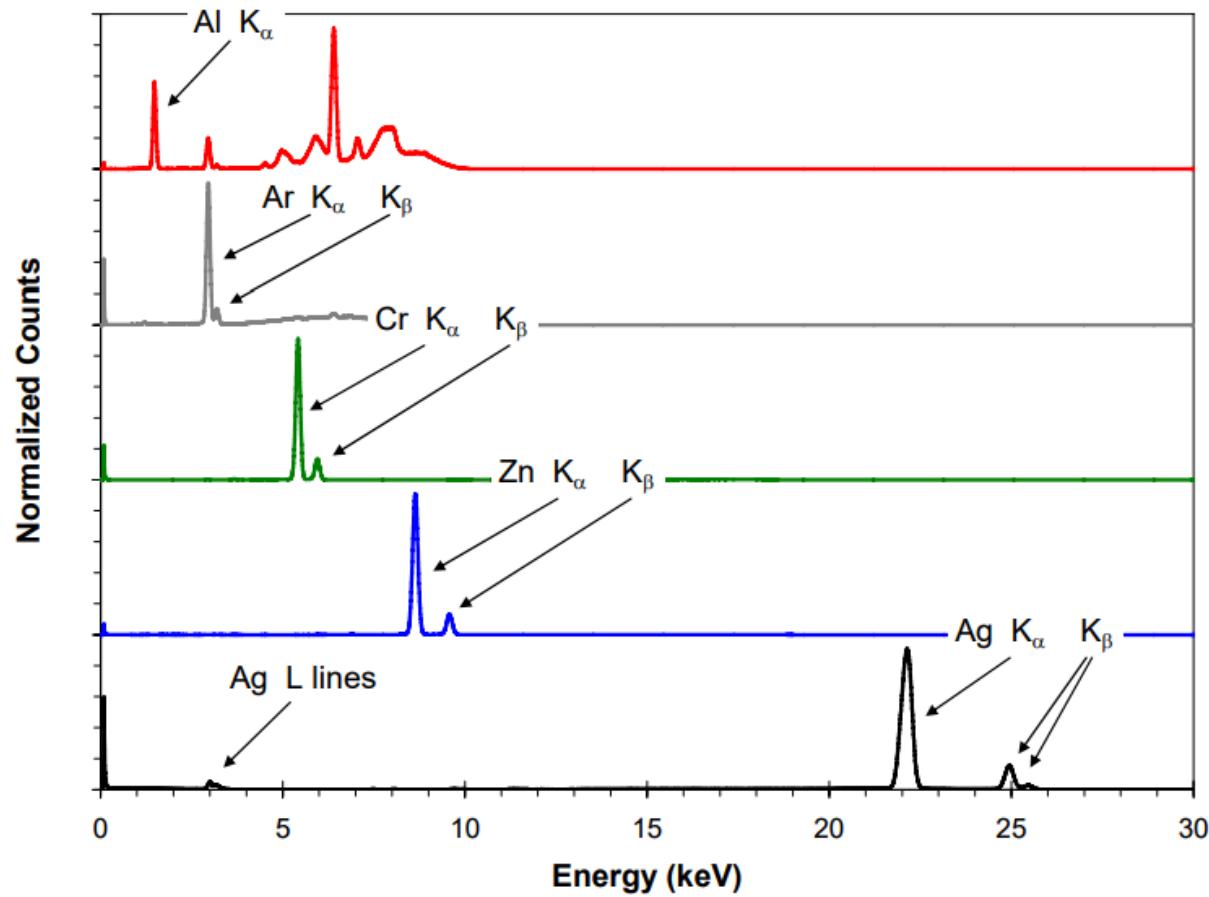
X荧光的原理



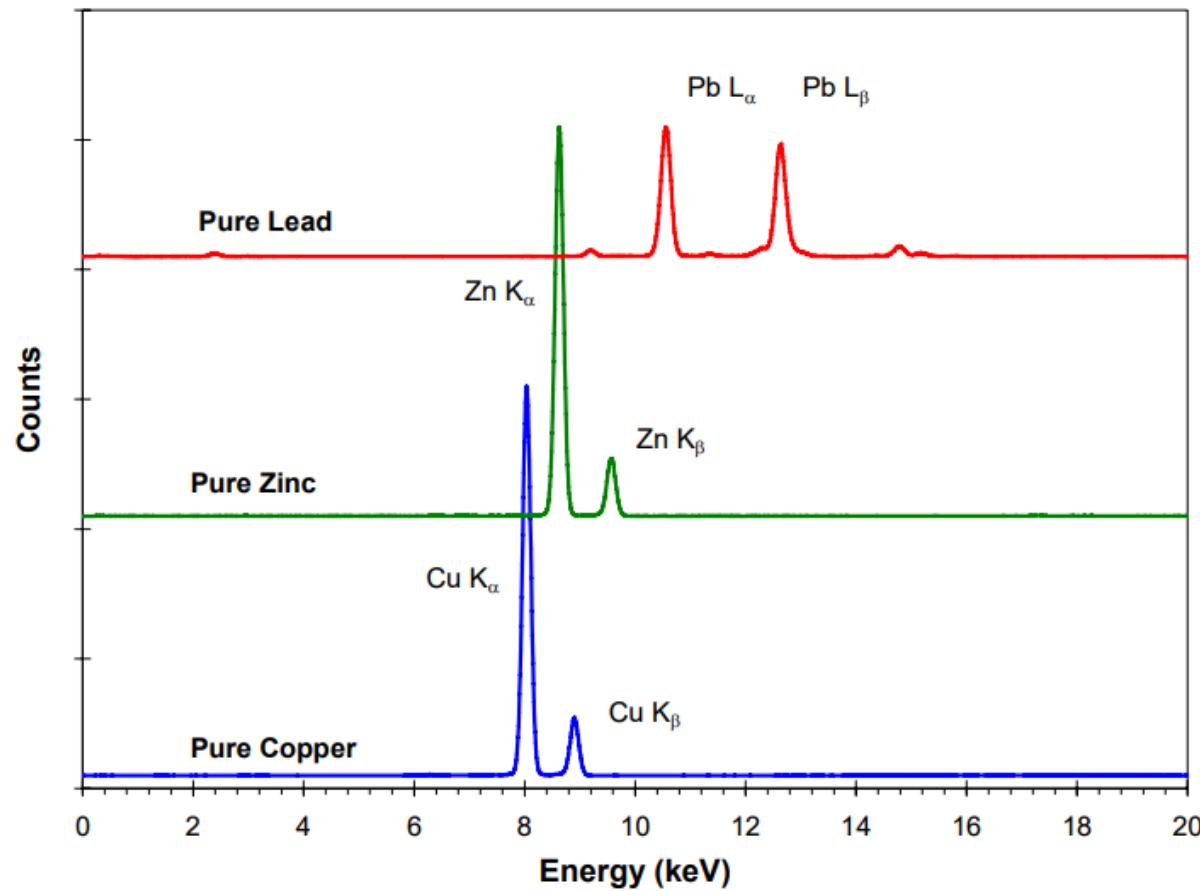
对被测样品发射一次X射线，样品的原子吸收X射线的能量后被激发并释放出二次X射线。

通过测量被释放出的二次X射线的特征能量和强度，就能够对被测样品的镀层厚度和成份进行定性和定量分析。

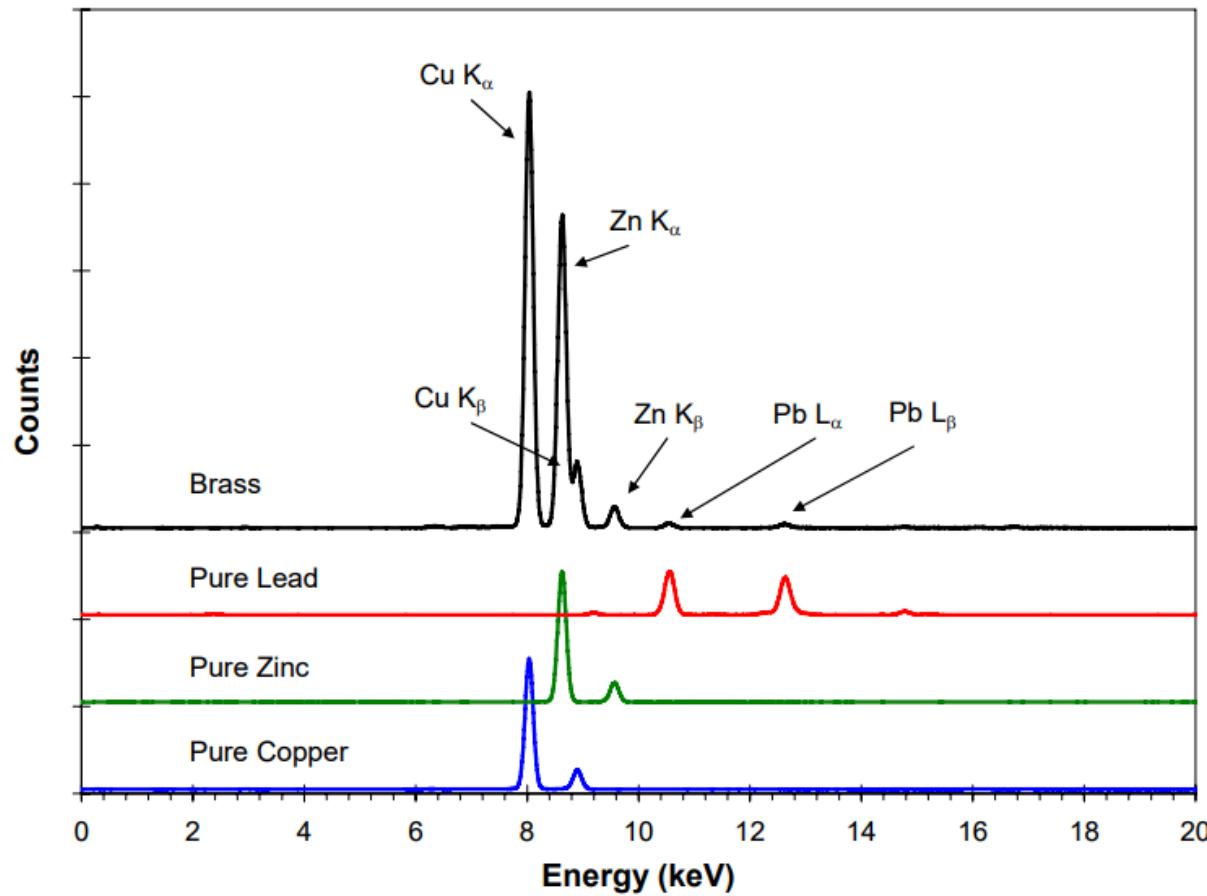
特征能量



纯金属的X荧光谱图



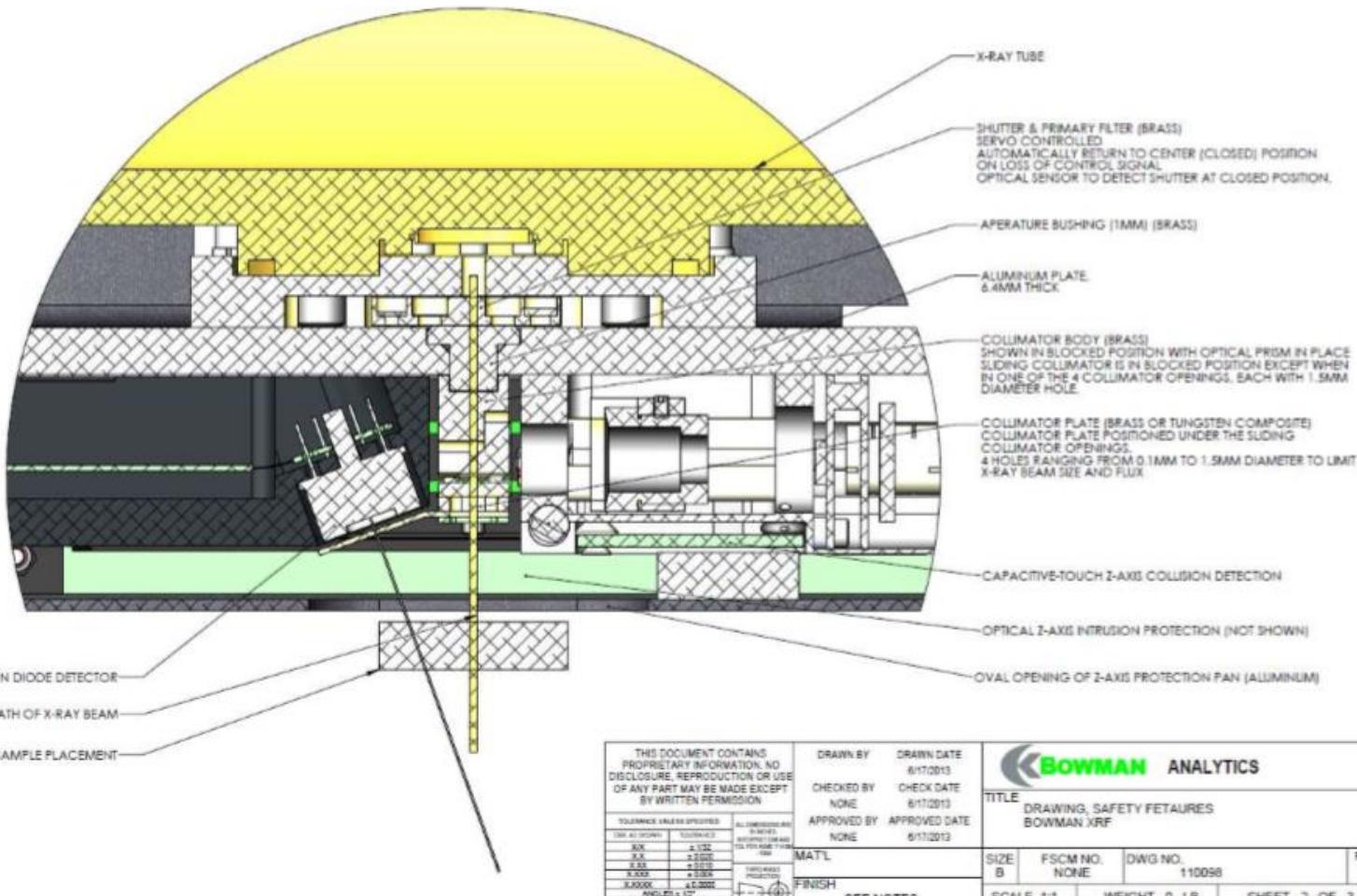
合金的X荧光谱图



X荧光定量分析方法

- Empirical 经验系数法
 $T = A I^B$
- Fundamental parameters 基本参数法

X荧光仪器系统



行业发展带来的新挑战

- Improved functionality
 - Phos analysis in electroless nickel
 - Alloyed plating
 - Solutions analysis
- Regulatory changes
 - Restriction of hazardous materials
- Tighter tolerance
 - Thinner coatings
 - Cost/material reduction
 - More thickness testing required
- Ongoing miniaturization of plated parts

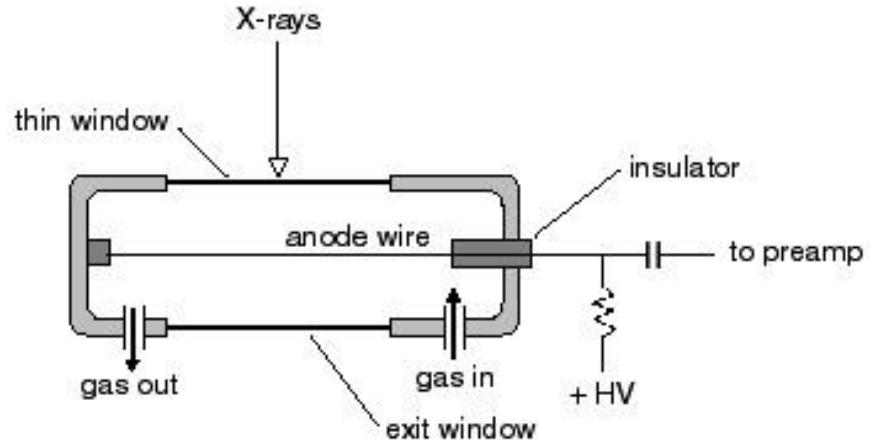
X荧光新技术

- Different types of detectors
 - Improved resolution
 - Improved stability
 - Prolonged life
- Various X-ray tube targets
 - Optimized for challenging applications
 - Cr, Mo, W, Rh, etc.
- X-ray optics
 - Poly capillary optics
 - Halo reduction optics
- Modular design
 - Miniaturized components
 - Low component cost
 - Better serviceability

检测器的发展

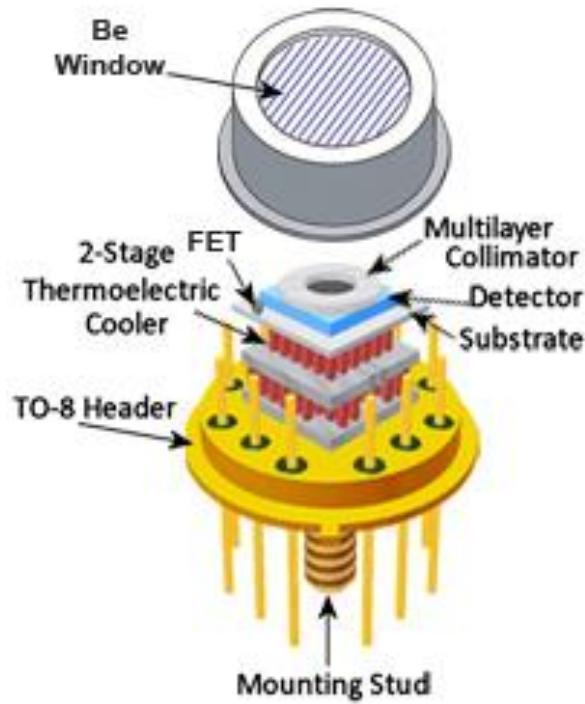
正比计数器

- Xe, Ne, or other halogen gas filled
- Drift with temperature or/and humidity change
- 10,000~30,000 cps
- 800~1200eV at Mn resolution
- Shorter life (2~5 years)



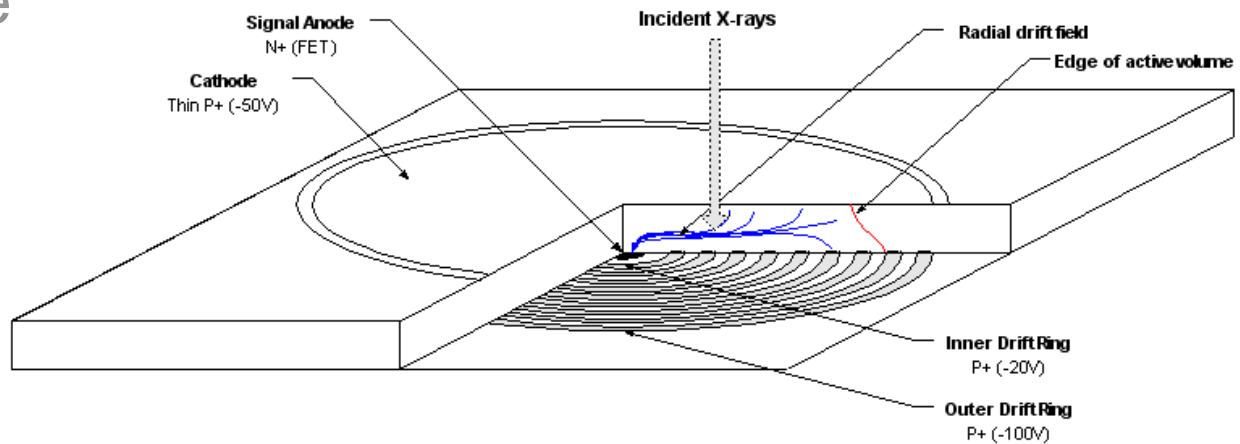
PIN 检测器

- Thermoelectrically cooled (Peltier)
- Be window
- Count rates:
3000~50,000 cps
- Resolution:
170~240eV at Mn K α
- 10+ years life

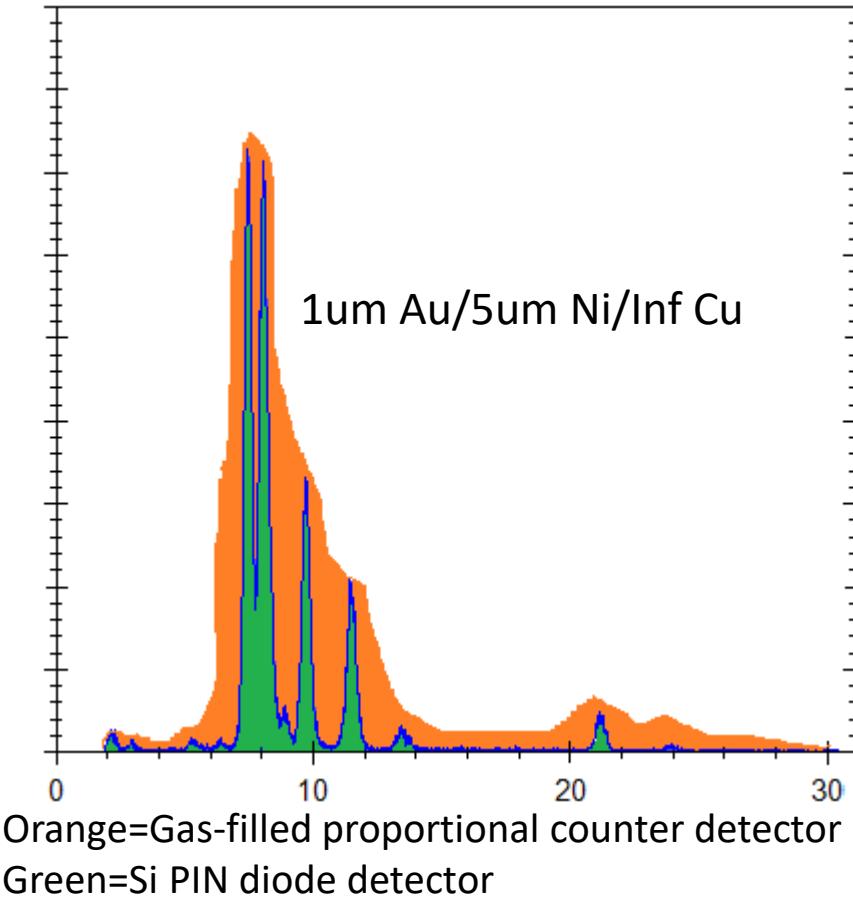


硅漂移检测器 (SDD)

- Thermoelectrically cooled (Peltier)
- Be window or Carbon based material
- Light element capability (i.e. P, Si, Al)
- Count rates: 10,000~1,000,000 cps
- Resolution: 120~170eV at Mn K α
- 10+ years life

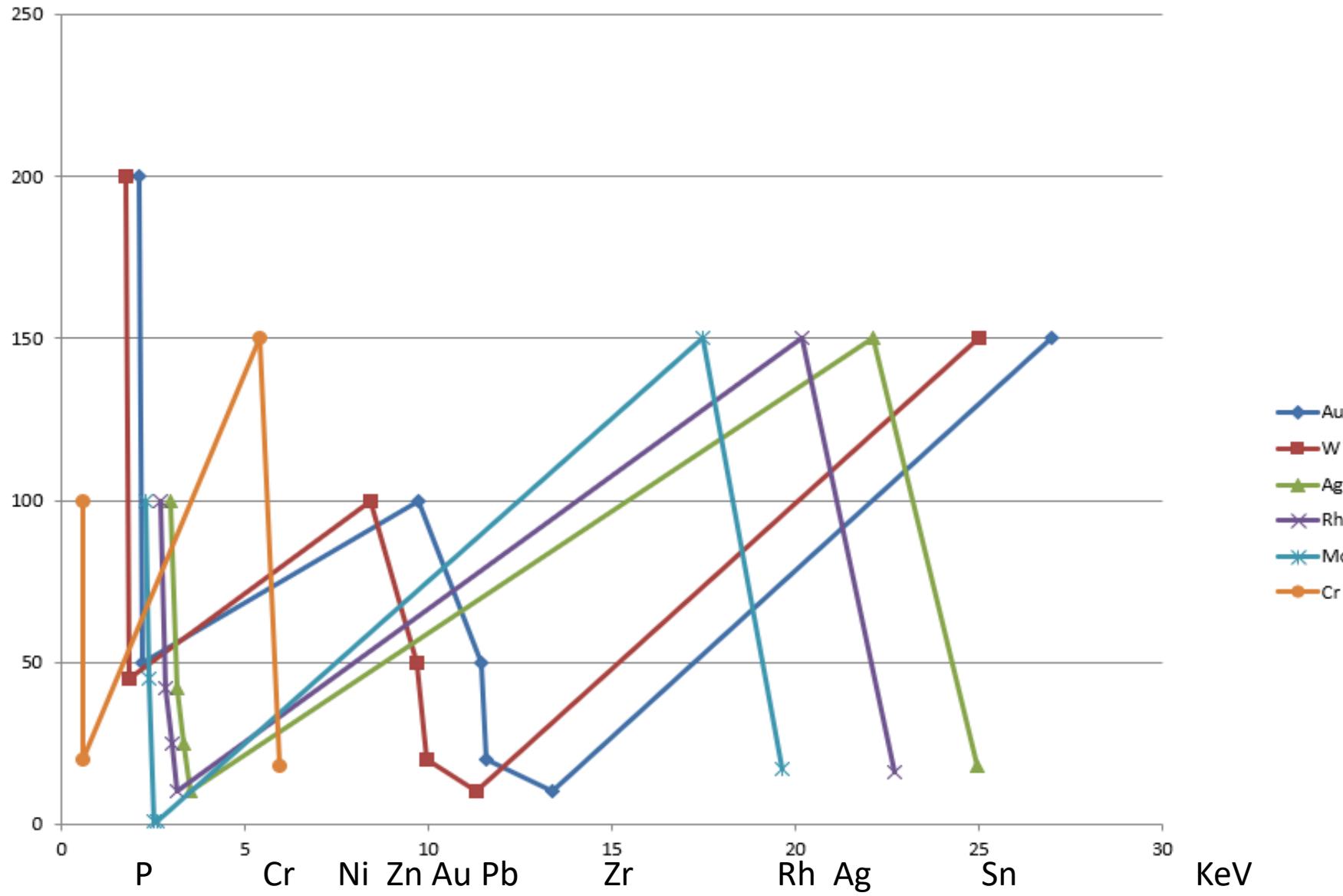


固态检测器的优点



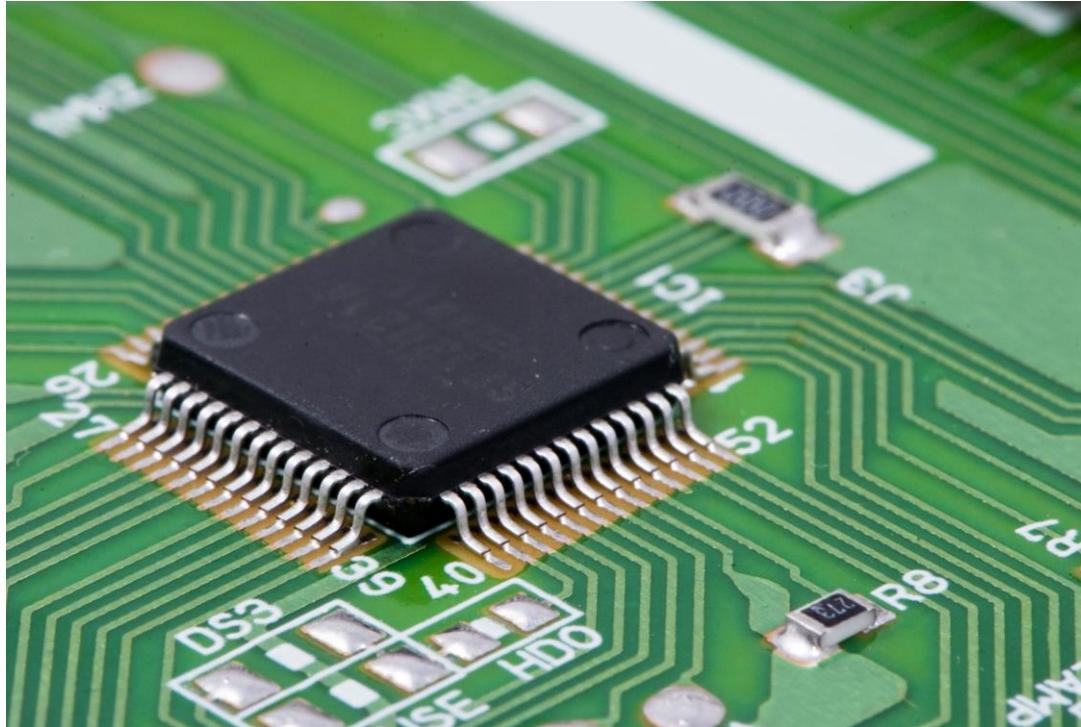
- Phosphorus analysis in electroless Ni
- Improved detection limits down to Angstrom or ppm level
- Separation of overlapping elements
- Improved stability with minimal drift
- Less maintenance

X射线管靶材



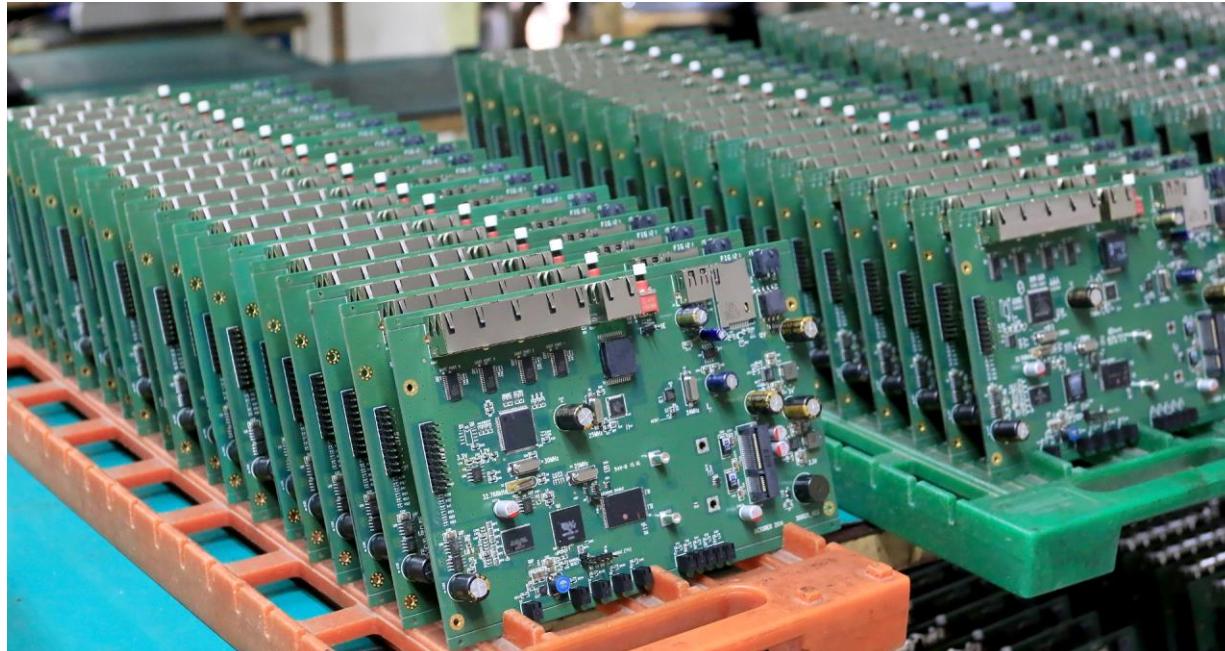
Optimized for challenging applications

- Cr
 - Thin Electroless Nickel (less than 10 micrometers Phos)



Optimized for challenging applications

- Mo
 - ENIG/ENEPIG
 - Immersion Ag



Optimized for challenging applications

- W
 - Zn, ZnNi; Transition metal plating



Optimized for challenging applications

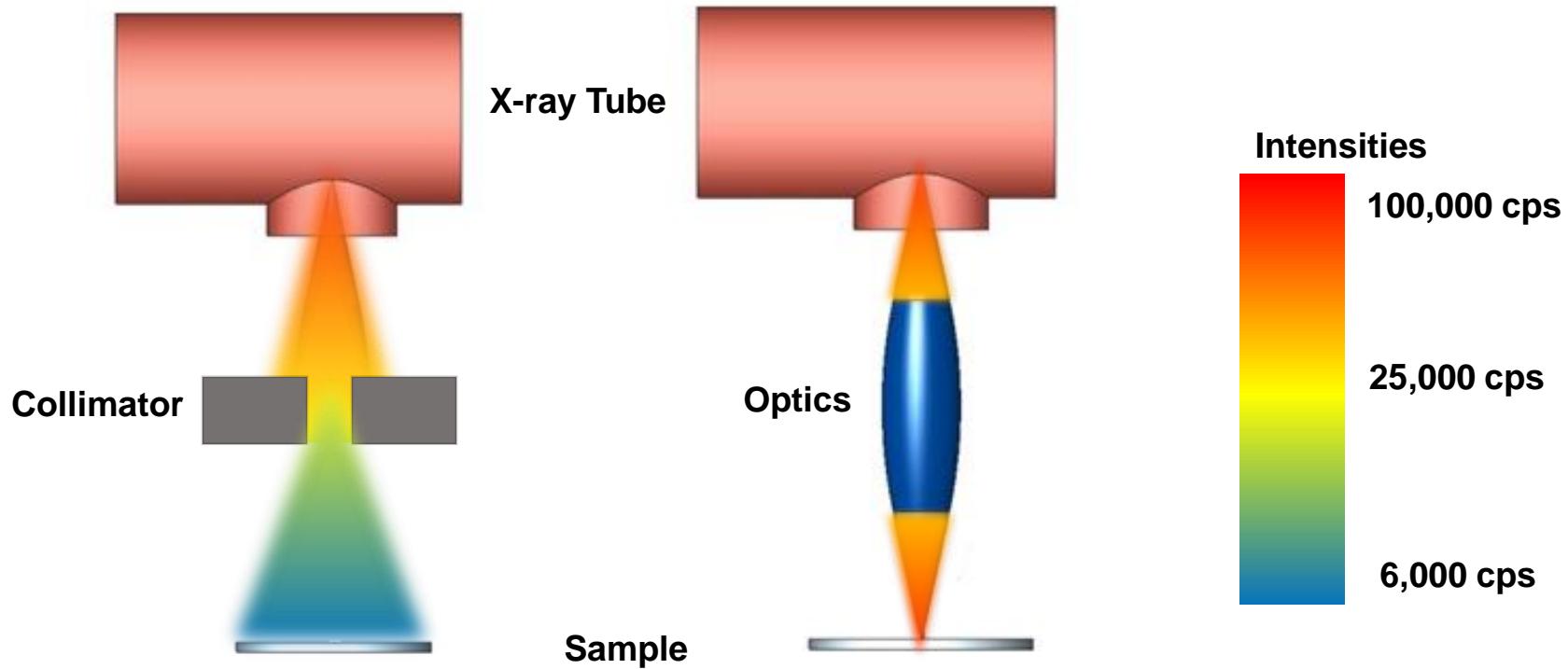
- Rh
 - Painting pretreatment



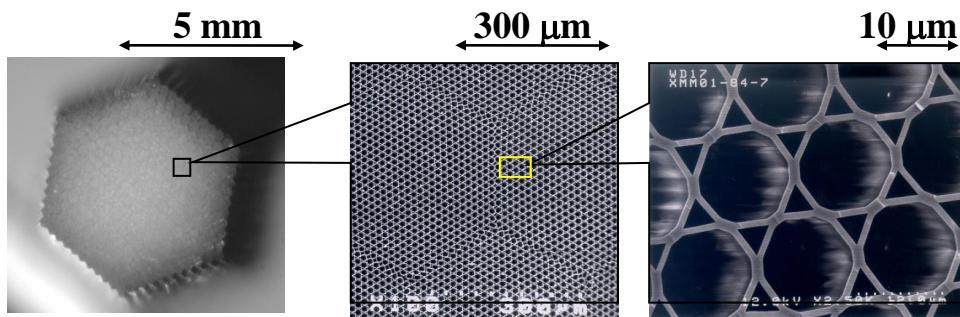
X射线光路

Reduce the inverse square loss

- Inverse square rule is a specified physical quantity where intensity is inversely proportional to the square of the distance from the source of that physical quantity.
- For analysis of feature as small as 15um



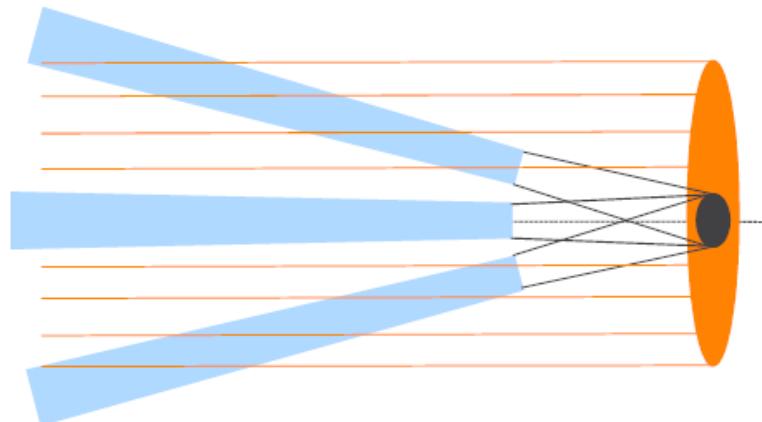
Poly-capillary focusing optics



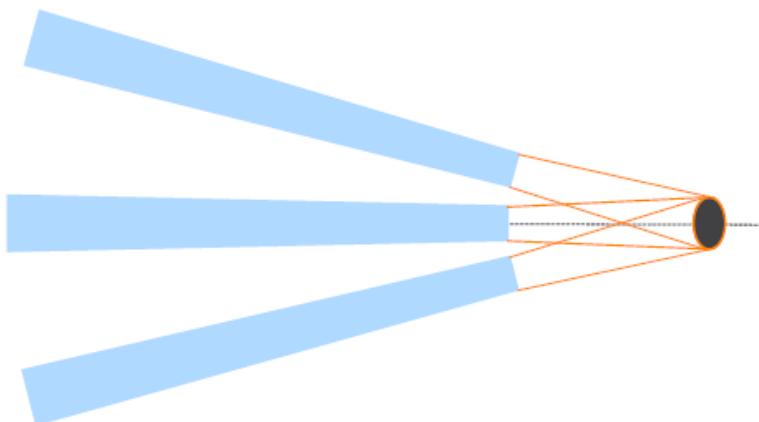
光晕效应

- Halo effect is due to high energy >20keV X-ray penetrating through the capillaries

Standard Optic



Halo Reduction Optic



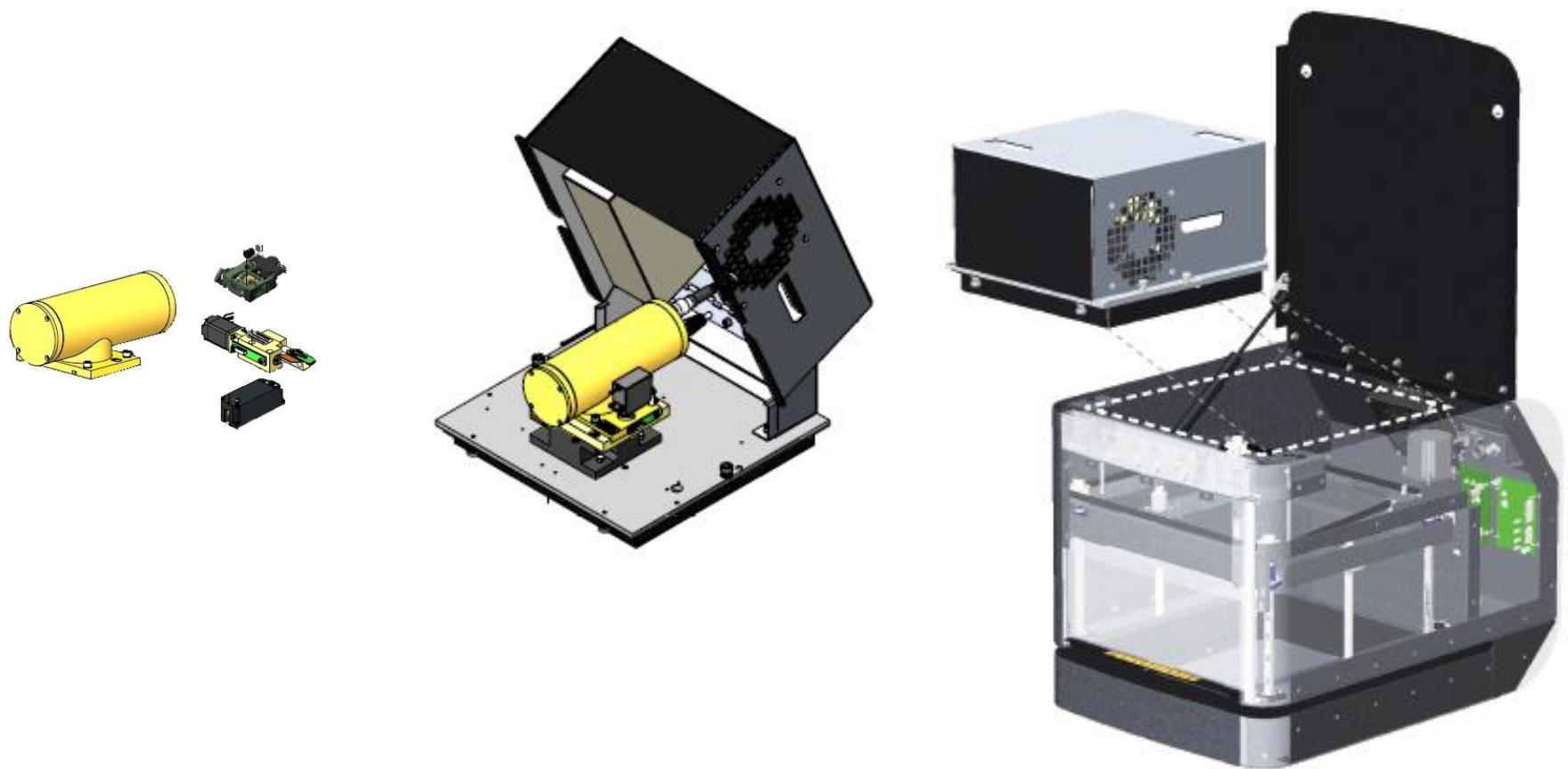
模块化设计

模块化设计

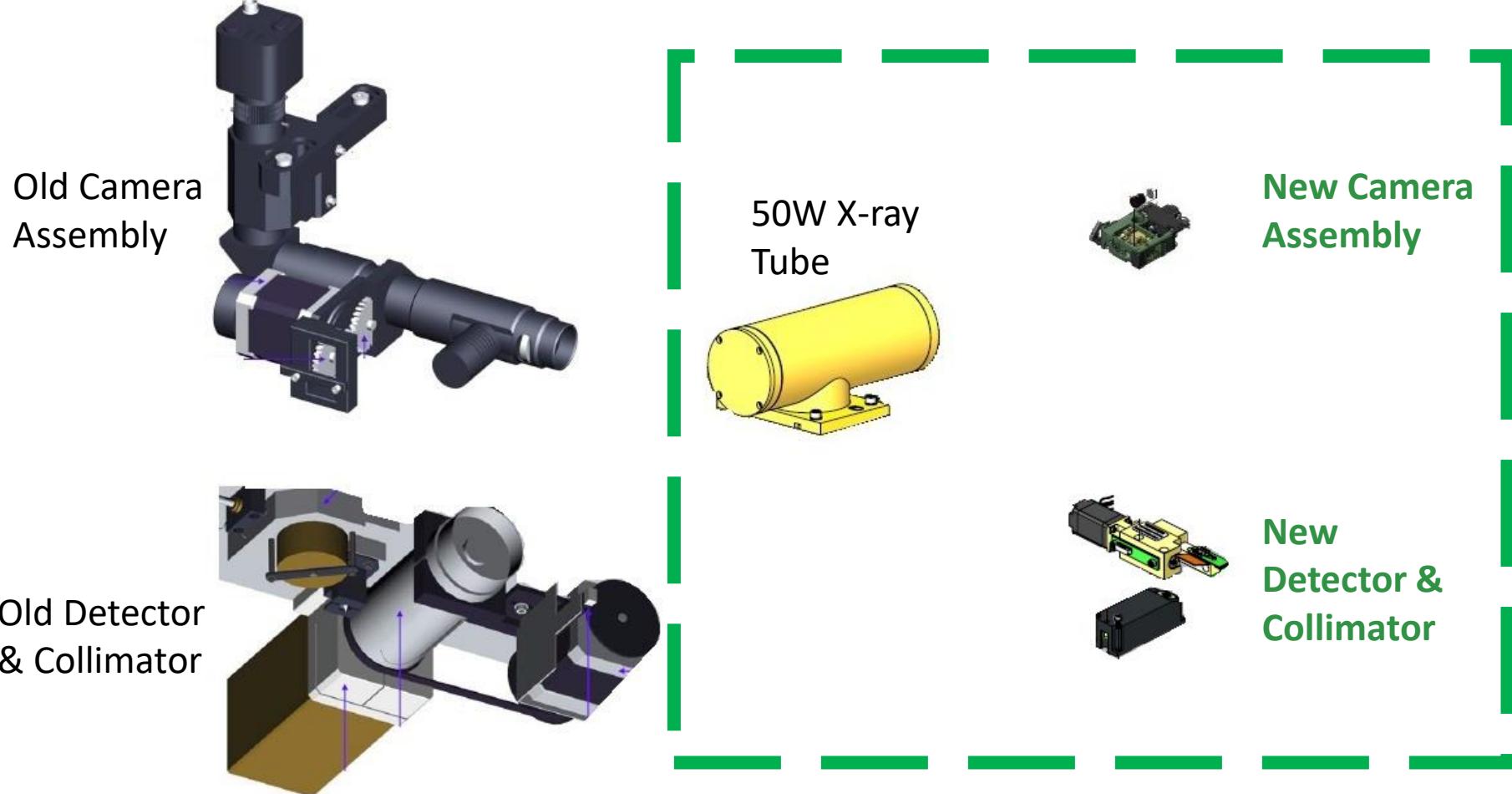
- All major components reside in “head”
- Head can be easily removed
- Minimize downtime
- Components can be upgraded at later date



模块化设计



更小的组件



Unique “smart modularity” provides significant advantages

- Upgradability
- Serviceability
- Downtime prevention
- Lower TCO



X荧光测厚仪的功能组件

- X-ray generation
- X-ray filtering
- X-ray collimation
- X-ray detection
- Sample vision
- Sample movement (robots)
- Machine vision (auto-focus, pattern recognition, image stitch, 2D barcode,...)
- User interface
- Software
- Report generator
- Fault protection
- X-ray safety

X荧光测厚仪的特点

1. 非接触，非破坏的无损检测方法
2. 可同时分析5层（4层镀层+基材）及合金层厚度。
如：Cr/Ni/Cu/ABS；ZnNi/Fe，Zn/Fe，Ni/Fe，NiCr/Cu/ABS，
.....
3. 测量范围广 13(Al) ~ 92(U)。
镀层厚度从几个nm ~ 100um左右可测
3. 样品无需前处理，可直接测量。。
4. 分析快速，可在几秒内测出结果
5. 具备成份分析功能，可同时测定25种元素。

